## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Akram et al.

Serial No.: 09/832,160

Filed: April 9, 2001

For: WAFER-LEVEL PACKAGE AND

METHODS OF FABRICATING

Confirmation No.: 8501

Examiner: D. Graybill

Group Art Unit: 2822

Attorney Docket No.: 2269-3846.2US

(98-0796.02/US)

**Notice of Allowance Mailed:** 

March 12, 2007

VIA ELECTRONIC FILING

June 11, 2007

## AMENDMENT PURSUANT TO 37 C.F.R. § 1.312(a)

Mail Stop ISSUE FEE Commissioner for Patents P.O. Box 1450 Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

Amendments to the specification begin on page 2 of this paper;

A listing of the claims begins on page 7 of this paper; and

Remarks start at page 10 of this paper.